

Innovating Robotics with Integrated Design of AI Computing and Motion Control

SEAVO Embedded Computer HB03



Promoting Large-Scale Application of Embodied Intelligence

The SEAVO Embedded Computer HB03 addresses the critical challenges of high-performance AI computing in constrained robotic environments. Its pioneering modular architecture combines Intel® Core™ Ultra processors (Series 2), with integrated NPU and iGPU (up to 96 TOPS) and expandable MXM GPU support (Intel® Arc™ B570, total 300 TOPS), enabling robotics for complex tasks like large language models, vision recognition, and motion control. HB03 has dual-size designs (150×142×53mm/78mm) and thin/thick versions, which is suitable for various forms of robots. With wide-voltage input (12V/48V), ruggedized I/O, and dual-fan cooling, it also ensures high reliability in dynamic scenarios.

The SEAVO Embedded Computer HB03 integrates CPU and GPU/NPU on a single motherboard, solves computing power bottlenecks and system redundancy, and enables large-scale practical application of embodied intelligence with strong performance, compact size, and high cost-effectiveness.

HB03 integrates CPU/GPU/NPU on one board to eliminate bottlenecks and scale embodied AI with compact, cost-effective power.

Intel Products and Technologies

Accelerating AI and Analytics at the Edge



Intel® Core™
Ultra Processors



OpenVINO™
Toolkit



Intel® Ethernet
Controller



Intel® oneAPI
Toolkit

Key Features

Empowered by Intel.



Modular Design



Compact Form Factor



Powerful AI Computing Capabilities



High Reliability

SEAVO Embedded Computer HB03



Product Specifications

CPU	Intel® Core™ Ultra processors (Series 2), with NPU and iGPU, up to 96TOPS
Graphics	Intel® Arc™ B570 Graphics
Memory	LPDDR5X-7467, 4*SDRAM, up to 64GB
Storage	1*M.2 M-Key 2280, PCIe4.0 x4
Wireless Network	1*M.2 E-Key 2230, PCIe x1 + USB2.0, support WiFi+BT 1*M.2 E-Key 3042/3052, USB3.0 + USB2.0, support 5G/4G module 1*Nano SIM
LAN	4*Intel® Ethernet Controller I210-AT NICs with EtherCAT Protocol, Type-C
Operating/Storage Temp.	0~60°C / -20 ~ 75°C
Dimension (W x D x H)	max: 150mm x 142mm x 78mm / min: 150mm x 142mm x 53mm
OS	Windows 10/11 64bit, Linux

Learn More

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